

## 1. General description

Planar passivated Silicon Controlled Rectifier in a TO247 plastic package intended for use in applications requiring very high inrush current capability and high thermal cycling performance.

## 2. Features and benefits

- High thermal cycling performance
- Planar passivated for voltage ruggedness and reliability
- High voltage capacity
- Very high current surge capability

## 3. Applications

- Line rectifying 50/60 Hz
- Softstart AC motor control
- DC Motor control
- Power converter
- AC power control
- Lighting and temperature control
- Uninterruptible Power Supply (UPS)
- Solid State Relay (SSR)
- Traction battery charging

## 4. Quick reference data

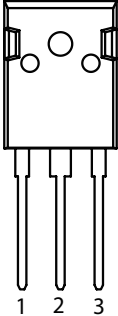

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Absolute maximum rating</b>						
$V_{DRM}$	repetitive peak off-state voltage		-	-	1400	V
$V_{RRM}$	repetitive peak reverse voltage		-	-	1400	V
$I_{T(RMS)}$	RMS on-state current	half sine wave; $T_{mb} \leq 129\text{ °C}$ ; <a href="#">Fig. 1</a> ; <a href="#">Fig. 2</a> ; <a href="#">Fig. 3</a>	-	-	79	A
$I_{TSM}$	non-repetitive peak on-state current	half sine wave; $T_{j(init)} = 25\text{ °C}$ ; $t_p = 10\text{ ms}$ ; <a href="#">Fig. 4</a> ; <a href="#">Fig. 5</a>	-	-	650	A
		half sine wave; $T_{j(init)} = 25\text{ °C}$ ; $t_p = 8.3\text{ ms}$	-	-	715	A
$T_j$	junction temperature		-	-	150	°C

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Static characteristics</b>						
$I_{GT}$	gate trigger current	$V_D = 12\text{ V}$ ; $I_T = 0.1\text{ A}$ ; $T_j = 25\text{ °C}$ ; <a href="#">Fig. 7</a> ; <a href="#">Fig. 8</a>	-	-	50	mA
<b>Dynamic characteristics</b>						
$dV_D/dt$	rate of rise of off-state voltage	$V_{DM} = 938\text{ V}$ ; $T_j = 125\text{ °C}$ ; Gate open circuit; ( $V_{DM} = 67\%$ of $V_{DRM}$ ); exponential waveform	1500	-	-	V/ $\mu$ s

## 5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode		
2	A	anode		
3	G	gate		
mb	A	mounting base; connected to anode		

## 6. Ordering information

Table 3. Ordering information

Type number	Package Name	Orderable part number	Packing method	Small packing quantity	Package version	Package issue date
TYN50W-1400T	TO247	TYN50W-1400TQ	Tube	30	TO247E	18-Jun-2021

## 7. Marking

Table 4. Marking codes

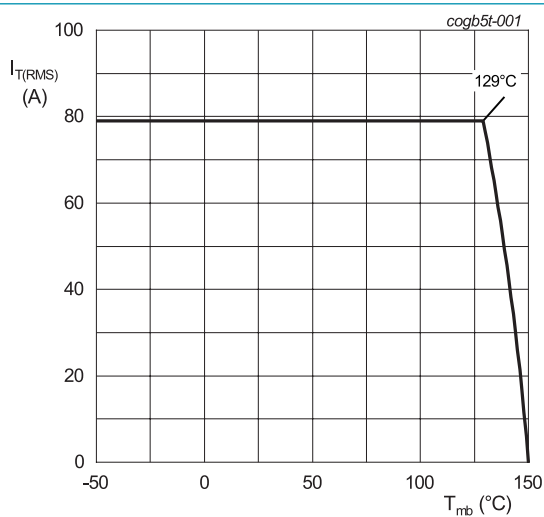
Type number	Marking codes
TYN50W-1400T	TYN50W 1400T

## 8. Limiting values

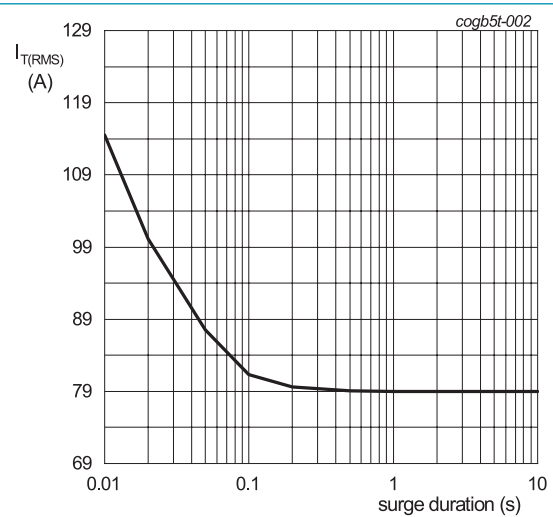
**Table 5. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

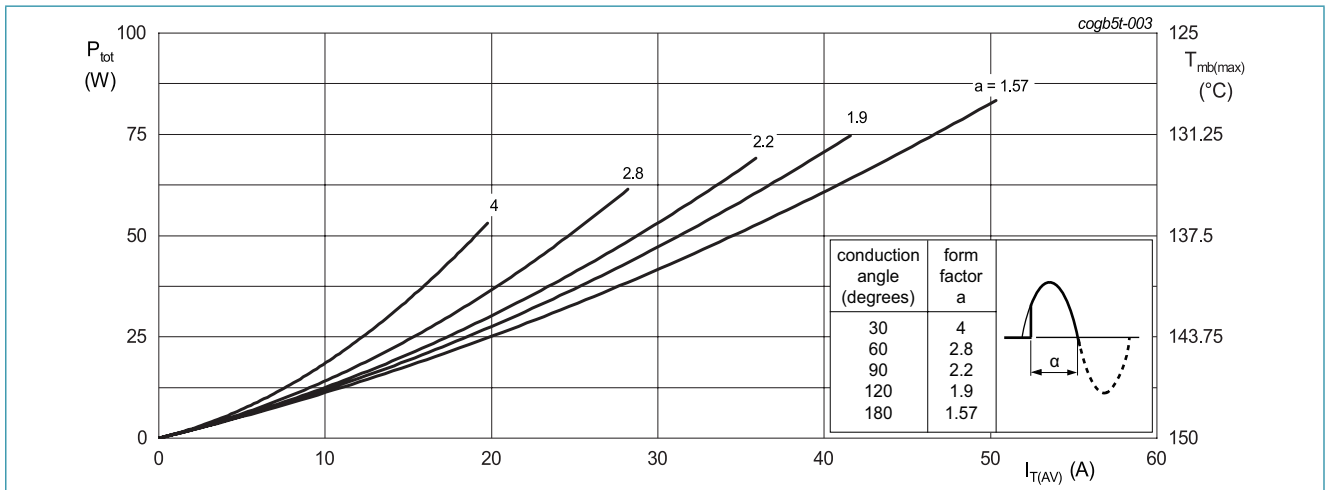
Symbol	Parameter	Conditions	Min	Max	Unit
$V_{DRM}$	repetitive peak off-state voltage		-	1400	V
$V_{RRM}$	repetitive peak reverse voltage		-	1400	V
$I_{T(AV)}$	average on-state current	half sine wave; $T_{mb} \leq 129\text{ °C}$	-	50	A
$I_{T(RMS)}$	RMS on-state current	half sine wave; $T_{mb} \leq 129\text{ °C}$ ; <a href="#">Fig 1</a> ; <a href="#">Fig 2</a> ; <a href="#">Fig 3</a>	-	79	A
$I_{TSM}$	non-repetitive peak on-state current	half sine wave; $T_{J(\text{init})} = 25\text{ °C}$ ; $t_p = 10\text{ ms}$ ; <a href="#">Fig 4</a> ; <a href="#">Fig 5</a>	-	650	A
		half sine wave; $T_{J(\text{init})} = 25\text{ °C}$ ; $t_p = 8.3\text{ ms}$	-	715	A
$I^2t$	$I^2t$ for fusing	$t_p = 10\text{ ms}$ ; sine-wave pulse	-	2113	A <sup>2</sup> s
$di_T/dt$	rate of rise of on-state current	$I_G = 200\text{mA}$	-	200	A/ $\mu\text{s}$
$I_{GM}$	peak gate current		-	8	A
$V_{RGM}$	peak reverse gate voltage		-	5	V
$P_{GM}$	peak gate power		-	20	W
$P_{G(AV)}$	average gate power	over any 20 ms period	-	1	W
$T_{stg}$	storage temperature		-40	150	°C
$T_j$	junction temperature		-	150	°C



**Fig. 1. RMS on-state current as a function of mounting base temperature; maximum values**

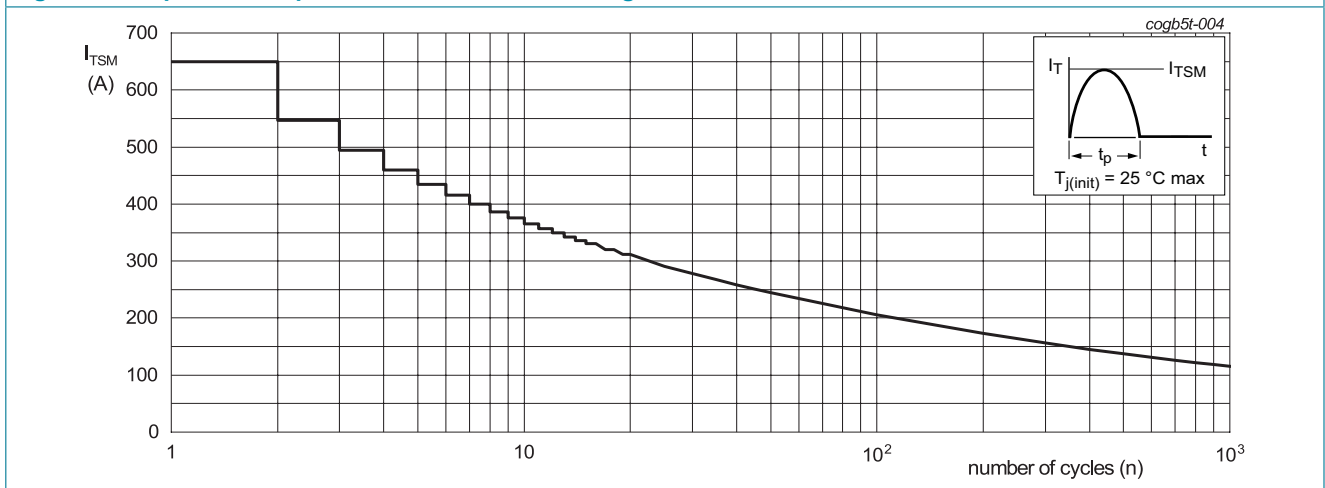


**Fig. 2. RMS on-state current as a function of surge duration; maximum values**  
 $f = 50\text{ Hz}$ ;  $T_{mb} = 129\text{ °C}$



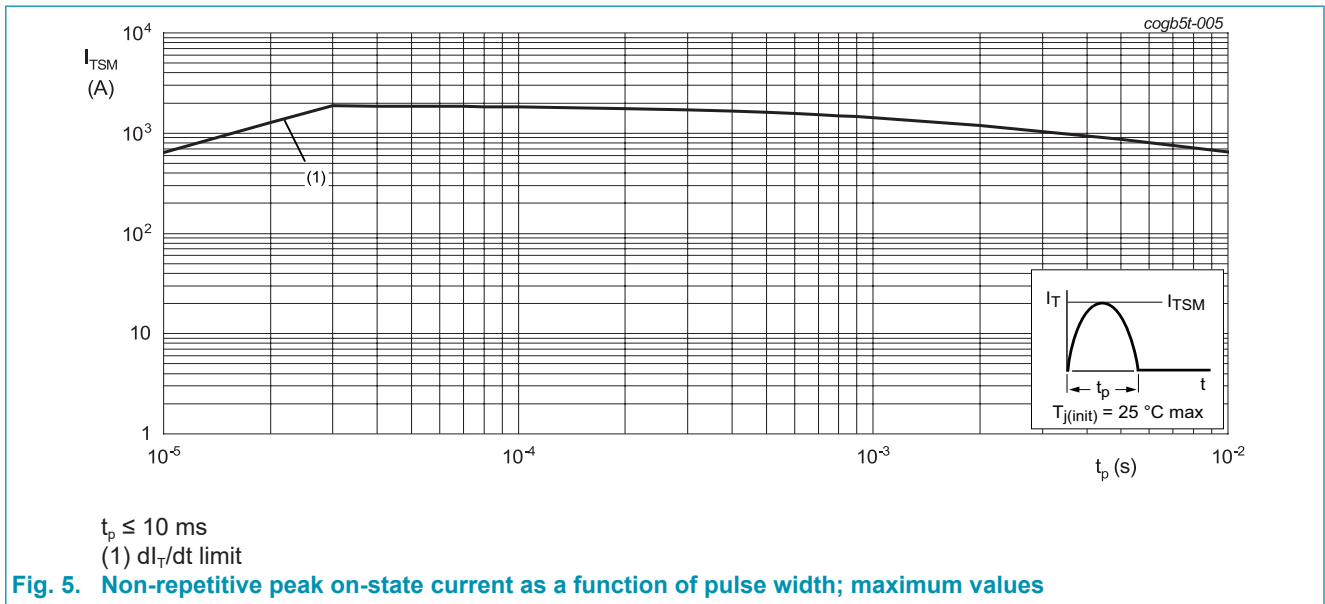
$\alpha$  = conduction angle  
 $a$  = form factor =  $I_{T(RMS)} / I_{T(AV)}$

Fig. 3. Total power dissipation as a function of average on-state current; maximum values



$f = 50\text{ Hz}$

Fig. 4. Non-repetitive peak on-state current as a function of the number of sinusoidal current cycles; maximum values



## 9. Thermal & Mechanical characteristics

Table 6. Thermal & Mechanical characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	<a href="#">Fig 6</a>	-	-	0.25	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient free air	in free air	-	50	-	K/W
	Mounting torque	M3 screw mounting	0.55	-	0.8	Nm

Note: It is recommended that a metal washer is inserted between screw head and mounting tab.  
Do not use self-tapping screws.

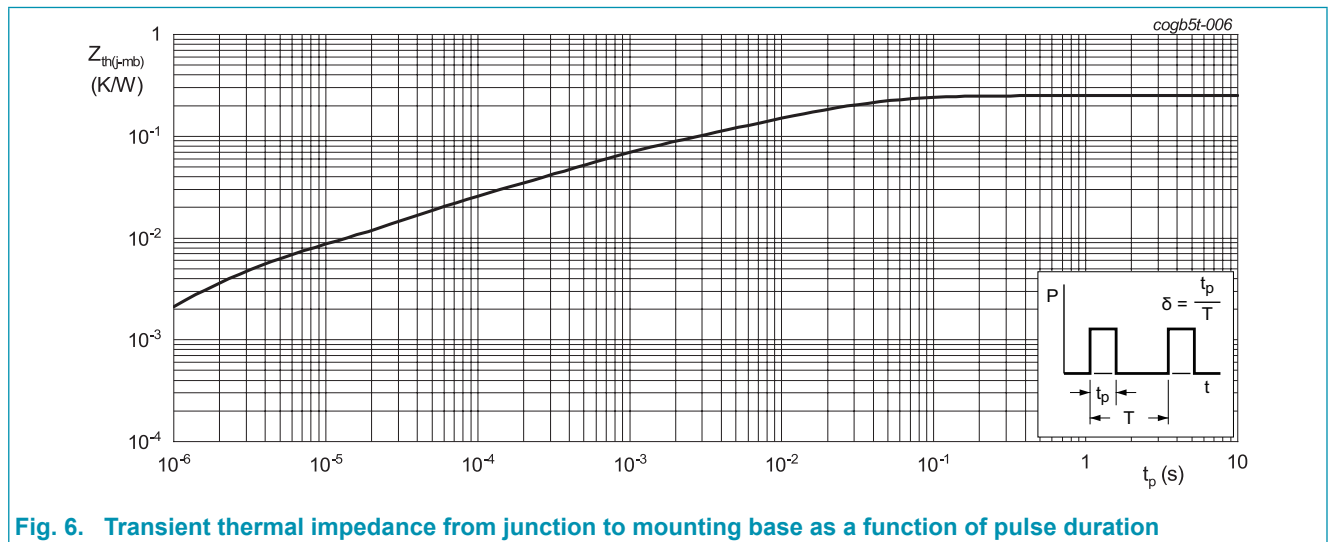


Fig. 6. Transient thermal impedance from junction to mounting base as a function of pulse duration

## 10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Static characteristics</b>						
$I_{GT}$	gate trigger current	$V_D = 12\text{ V}$ ; $I_T = 0.1\text{ A}$ ; $T_j = 25\text{ °C}$ ; <a href="#">Fig. 7</a> ; <a href="#">Fig. 8</a>	-	-	50	mA
$I_L$	latching current	$V_D = 12\text{ V}$ ; $I_G = 0.1\text{ A}$ ; $T_j = 25\text{ °C}$ ; <a href="#">Fig. 9</a>	-	-	300	mA
$I_H$	holding current	$V_D = 12\text{ V}$ ; $T_j = 25\text{ °C}$ ; <a href="#">Fig. 10</a>	-	-	200	mA
$V_T$	on-state voltage	$I_T = 50\text{ A}$ ; $T_j = 25\text{ °C}$ ; <a href="#">Fig. 11</a>	-	-	1.35	V
		$I_T = 79\text{ A}$ ; $T_j = 25\text{ °C}$ ; <a href="#">Fig. 11</a>	-	-	1.5	V
$V_{GT}$	gate trigger voltage	$V_D = 12\text{ V}$ ; $I_T = 0.1\text{ A}$ ; $T_j = 25\text{ °C}$ ; <a href="#">Fig. 12</a>	-	0.7	1	V
		$V_D = 800\text{ V}$ ; $I_T = 0.1\text{ A}$ ; $T_j = 125\text{ °C}$	0.25	0.4	-	V
$I_D$	off-state current	$V_D = 1400\text{ V}$ ; $T_j = 25\text{ °C}$	-	-	10	$\mu\text{A}$
		$V_D = 1400\text{ V}$ ; $T_j = 150\text{ °C}$	-	-	10	mA
$I_R$	reverse current	$V_D = 1400\text{ V}$ ; $T_j = 25\text{ °C}$	-	-	10	$\mu\text{A}$
		$V_D = 1400\text{ V}$ ; $T_j = 150\text{ °C}$	-	-	10	mA
<b>Dynamic characteristics</b>						
$dV_D/dt$	rate of rise of off-state voltage	$V_{DM} = 938\text{ V}$ ; $T_j = 125\text{ °C}$ ; Gate open circuit; ( $V_{DM} = 67\%$ of $V_{DRM}$ ); exponential waveform	1500	-	-	$\text{V}/\mu\text{s}$
		$V_{DM} = 938\text{ V}$ ; $T_j = 150\text{ °C}$ ; Gate open circuit; ( $V_{DM} = 67\%$ of $V_{DRM}$ ); exponential waveform	1000	-	-	$\text{V}/\mu\text{s}$
$t_{gt}$	gate-controlled turn-on time	$I_{TM} = 40\text{ A}$ ; $V_D = 800\text{ V}$ ; $I_G = 0.1\text{ A}$ ; $dI_G/dt = 5\text{ A}/\mu\text{s}$ ; $T_j = 25\text{ °C}$	-	2	-	$\mu\text{s}$
$t_q$	commutated turn-off time	$V_{DM} = 938\text{ V}$ ; $T_j = 125\text{ °C}$ ; $I_{TM} = 20\text{ A}$ ; $V_R = 25\text{ V}$ ; $(dI_T/dt)_M = 30\text{ A}/\mu\text{s}$ ; $dV_D/dt = 50\text{ V}/\mu\text{s}$ ; $R_{GK(ext)} = 100\text{ k}\Omega$ ; ( $V_{DM} = 67\%$ of $V_{DRM}$ )	-	150	-	$\mu\text{s}$

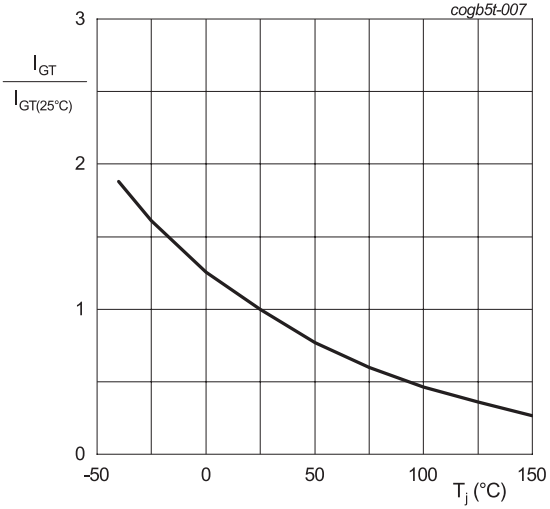


Fig. 7. Normalized gate trigger current as a function of junction temperature

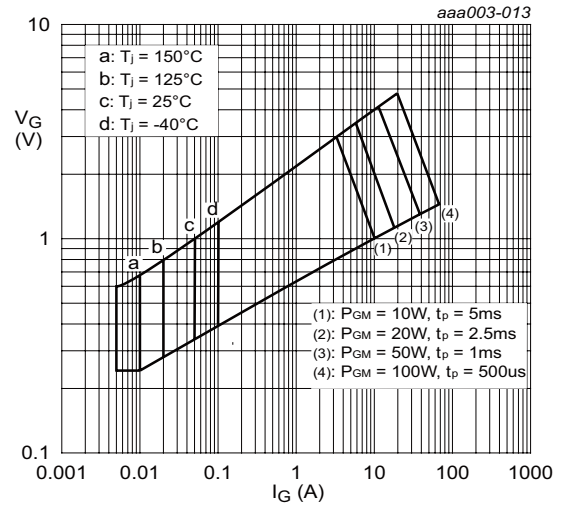


Fig. 8. Gate voltage as a function of gate current

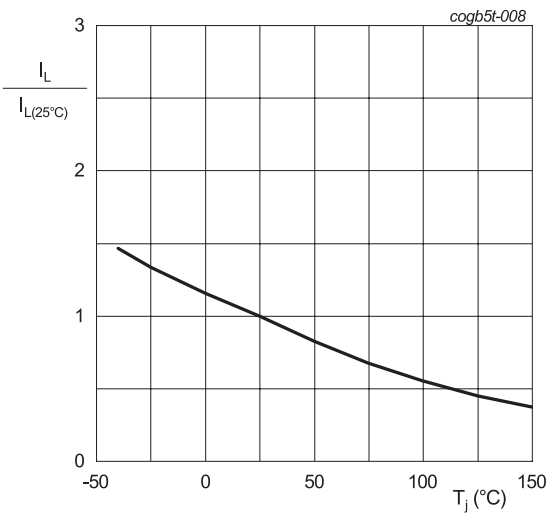


Fig. 9. Normalized latching current as a function of junction temperature

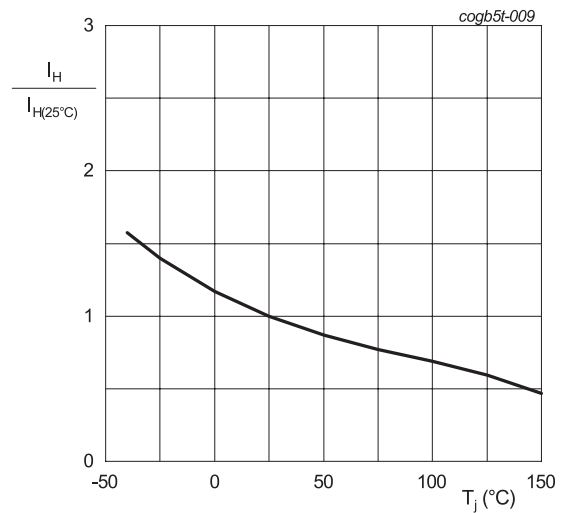
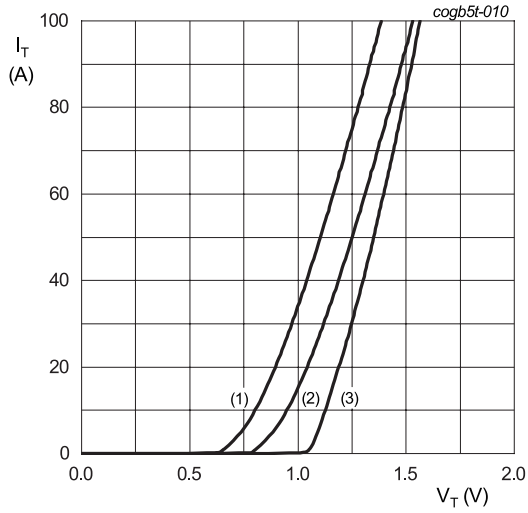


Fig. 10. Normalized holding current as a function of junction temperature





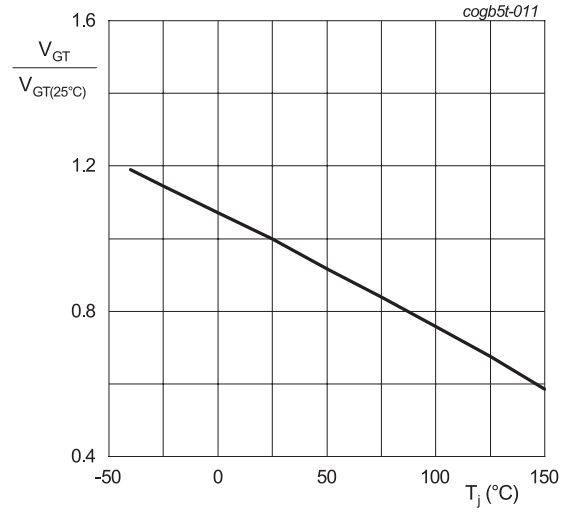
$V_o = 0.992 \text{ V}$ ;  $R_s = 0.0054 \text{ } \Omega$

(1)  $T_j = 150 \text{ } ^\circ\text{C}$ ; typical values

(2)  $T_j = 150 \text{ } ^\circ\text{C}$ ; maximum values

(3)  $T_j = 25 \text{ } ^\circ\text{C}$ ; maximum values

**Fig. 11. On-state current as a function of on-state voltage**

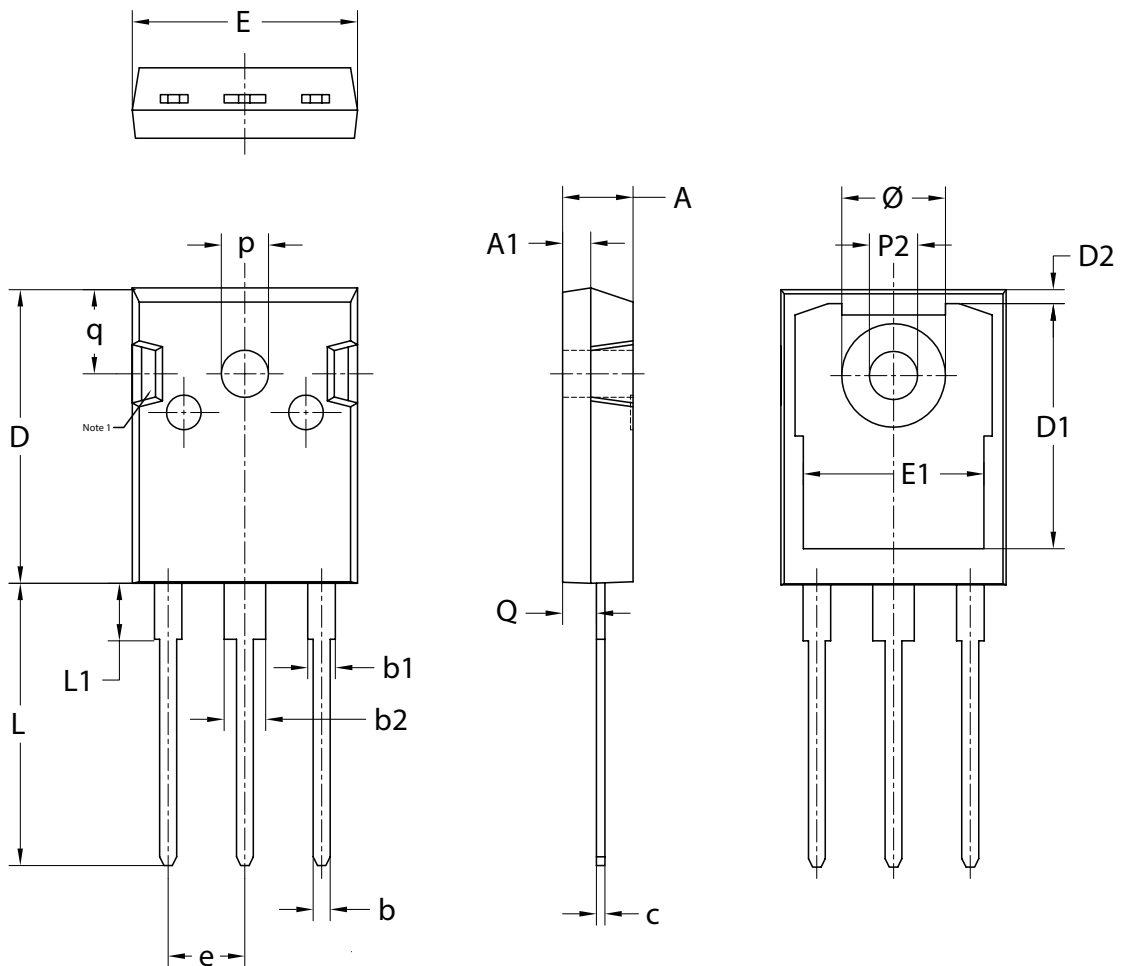


**Fig. 12. Normalized gate trigger voltage as a function of junction temperature**

### 11. Package outline

Plastic single-ended through-hole package; heatsink mounted; 1 mounting hole; 3 leads TO-247

TO247



UNIT	A	A1	b	b <sub>1</sub>	b <sub>2</sub>	c	D	D1	D2	E	E1	e	L	L1	P2	p	Q	q	Ø
mm	5.36	2.10	1.40	2.30	3.30	0.72	21.80	17.10	1.36	16.20	13.52	5.44	20.50	4.35	3.64	3.85	2.60	6.58	7.30
	4.68	1.90	1.00	1.90	2.90	0.48	20.80	16.10	0.80	15.38	13.00	BSC	19.50	3.75	3.24	3.45	2.30	5.99	7.10

Note:

1. Metal exposed with Sn plating.
2. Dimension D&E do not include mold flash and gate remain

## 12. Legal information

### Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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